

Fig. 1

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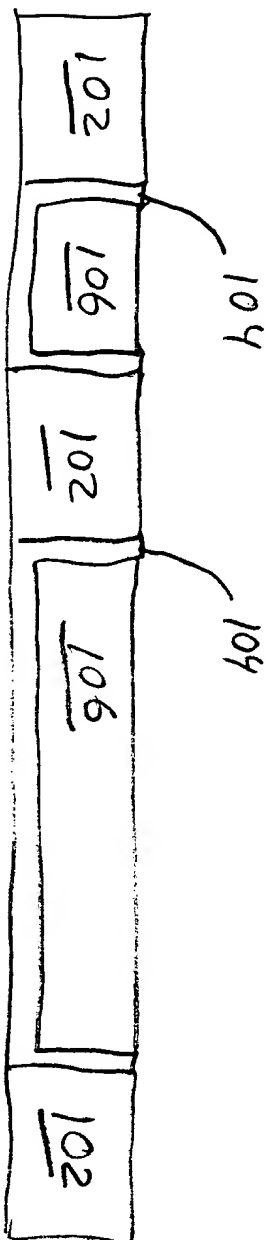


Fig. 2

Provide a slurry having an abrasive harder than a first layer and less hard than an underlying second layer to polishing pad

Bring substrate with first layer thereon into contact with polishing pad

### Polish first layer

Stop polish on second layer

Fig. 3